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**Declarations under Rule 4.17**:

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— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

*[Continued on next page]*

(54) Title: METALLIZATION PROCESSES, MIXTURES, AND ELECTRONIC DEVICES

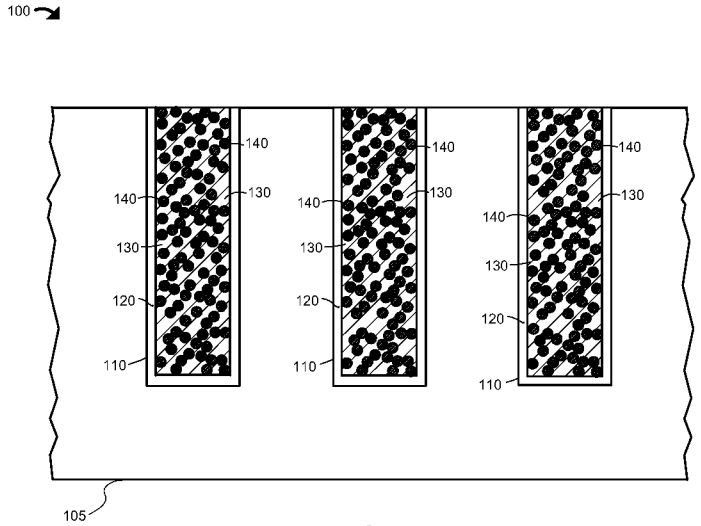



FIG. 2

(57) Abstract: One aspect of the present invention is a method of processing a substrate. In one embodiment, the method comprises forming an electrical conductor on or in the substrate by providing a mixture comprising metal particles and an electroless deposition solution and electrolessly depositing a metal matrix and co-depositing the metal particles. In another embodiment, the method comprises forming an electrical conductor on or in the substrate by providing a mixture comprising metal particles and an electrochemical plating solution and electrochemically plating a metal matrix and co-depositing the metal particles. Another aspect of the present invention is a mixture for the formation of an electrical conductor on or in a substrate. Another aspect of the present invention is an electronic device.

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